NPN DUAL SMALL SIGNAL SURFACE MOUNT TRANSISTOR

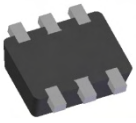
Features

- Epitaxial Die Construction
- Ultra-Small Surface Mount Package
- **Lead Free By Design/RoHS Compliant (Note 3)**
- **"Green" Device (Note 4)**
- **Qualified to AEC-Q101 Standards for High Reliability**

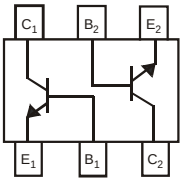
Mechanical Data

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Finish - Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.002 grams (approximate)

Top View



Bottom View



Device Schematic

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	50	V
Collector-Emitter Voltage	V_{CEO}	45	V
Emitter-Base Voltage	V_{EBO}	6.0	V
Collector Current	I_C	100	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	P_D	150	mW
Thermal Resistance, Junction to Ambient (Note 2)	$R_{\theta JA}$	833	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	(Note 5)	$V_{(BR)CBO}$	50	—	—	V	I_C = 10μA, I_B = 0
Collector-Emitter Breakdown Voltage	(Note 5)	$V_{(BR)CEO}$	45	—	—	V	I_C = 10mA, I_B = 0
Emitter-Base Breakdown Voltage	(Note 5)	$V_{(BR)EBO}$	6	—	—	V	I_E = 1μA, I_C = 0
DC Current Gain	(Note 5)	h_{FE}	200	290	450	—	V_{CE} = 5.0V, I_C = 2.0mA
Collector-Emitter Saturation Voltage	(Note 5)	$V_{CE(SAT)}$	—	—	100 300	mV	I_C = 10mA, I_B = 0.5mA I_C = 100mA, I_B = 5.0mA
Base-Emitter Saturation Voltage	(Note 5)	$V_{BE(SAT)}$	—	700 900	—	mV	I_C = 10mA, I_B = 0.5mA I_C = 100mA, I_B = 5.0mA
Base-Emitter Voltage	(Note 5)	V_{BE}	580 —	660 —	700 770	mV	V_{CE} = 5.0V, I_C = 2.0mA V_{CE} = 5.0V, I_C = 10mA
Collector-Emitter Cutoff Current	(Note 5)	I_{CBO} I_{CBO}	—	—	15 5.0	nA μA	V_{CB} = 30V V_{CB} = 30V, T_A = 150°C
Gain Bandwidth Product		f_T	100	—	—	MHz	V_{CE} = 5.0V, I_C = 10mA, f = 100MHz
Output Capacitance		C_{OBO}	—	—	4.5	pF	V_{CB} = 10V, f = 1.0MHz
Noise Figure		NF	—	—	10	dB	V_{CE} = 5V, R_S = 2.0kΩ, f = 1.0kHz, BW = 200Hz

Notes:
1. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways).
2. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
3. No purposefully added lead.
4. Diodes Inc's "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php
5. Short duration pulse test used to minimize self-heating effect.

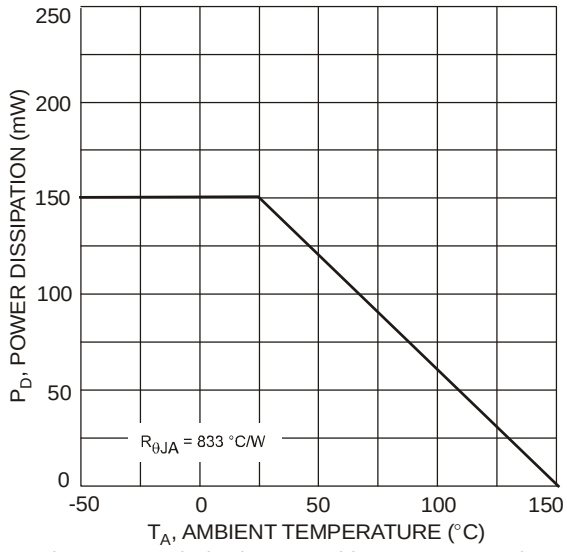


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 2)

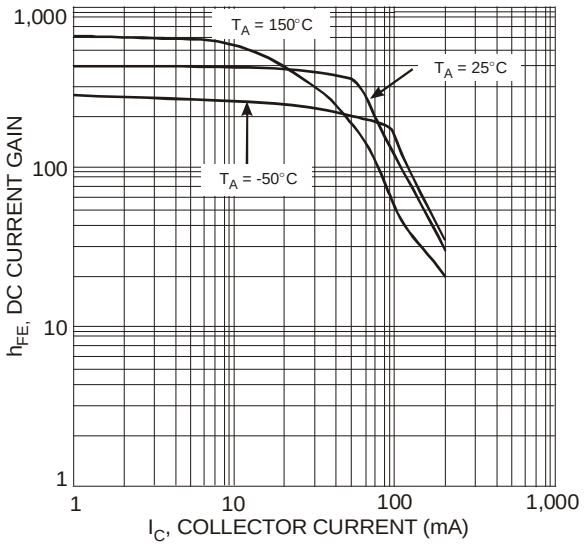


Fig. 2 Typical DC Current Gain vs. Collector Current

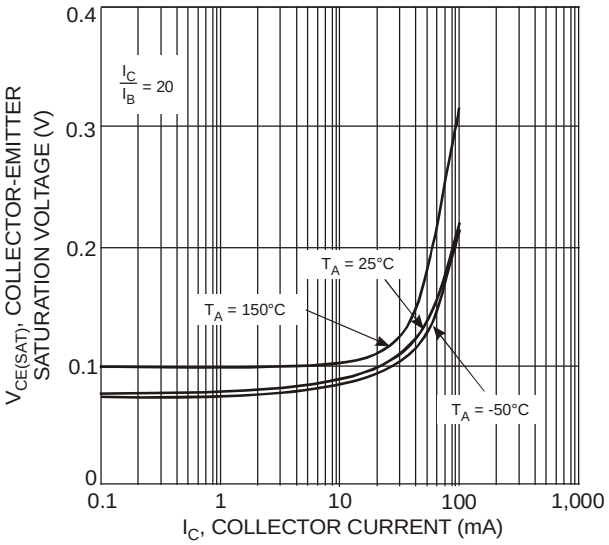


Fig. 3 Typical Collector Emitter Saturation Voltage vs. Collector Current

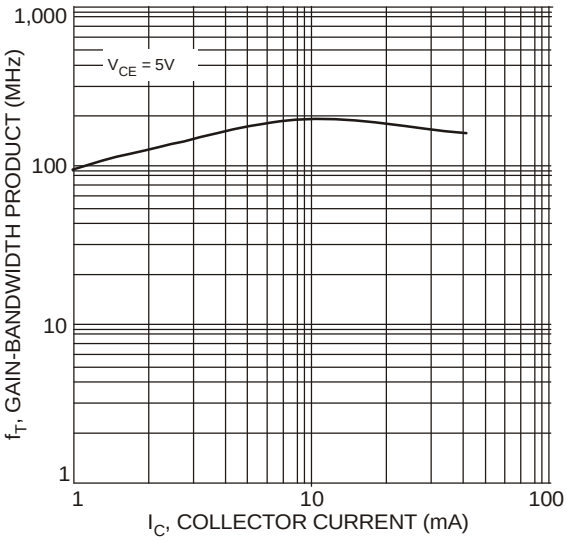


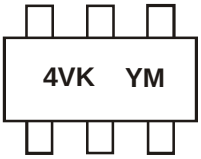
Fig. 4 Typical Gain-Bandwidth Product vs. Collector Current

Ordering Information (Note 6)

Part Number	Case	Packaging
BC847BVC-7	SOT-563	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



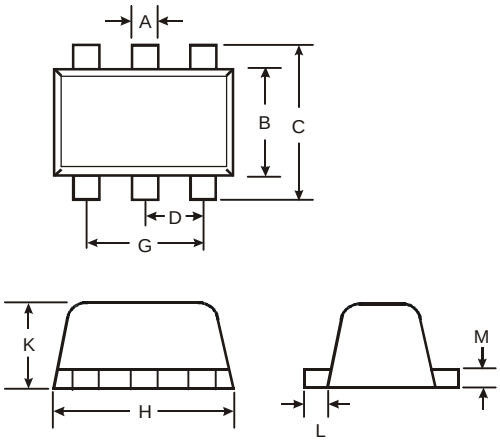
4VK = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: S = 2005)
M = Month (ex: 9 = September)

Date Code Key

Year	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	S	T	U	V	W	X	Y	Z	A	B	C

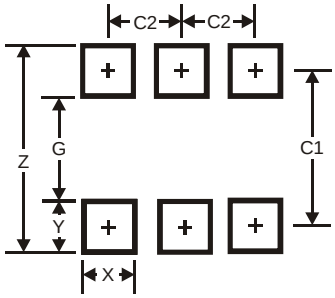
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-563			
Dim	Min	Max	Typ
A	0.15	0.30	0.20
B	1.10	1.25	1.20
C	1.55	1.70	1.60
D	-	-	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
K	0.55	0.60	0.60
L	0.10	0.30	0.20
M	0.10	0.18	0.11
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

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